L Number	Hits	Search Text	DB	Time stamp
1	2124099	(integrated adj circuit) ic semiconductor die chip dice	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/06/28 11:07
2	579735	flipchip (flip adj chip) bumps balls standoff	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/06/28
3	1575	257/686	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28
4	0	257/6856	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/06/28
5	734	257/685	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28
6	2481	257/723	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28
7	1398	257/777	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28 11:08
8	2304	257/778	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28
9	1931	257/737	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28
10	1543	257/738	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28
11	1641	257/784	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28 11:08
12	1783	257/786	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/06/28
13	2602195	((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:09

14	8954	257/686 257/685 257/723 257/777 257/778	USPAT;	2002/06/28
	•	257/737 257/738 257/784 257/786	US-PGPUB;	11:09
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	124853	438/\$7.ccls.	USPAT;	2002/06/28
			US-PGPUB;	11:09
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	91119	361/\$7.ccls.	USPAT;	2002/06/28
			US-PGPUB;	11:09
			EPO; JPO;	
]			DERWENT;	İ
	:		IBM_TDB	
17	4715	(flipchip (flip adj chip) bumps balls	USPAT;	2002/06/28
		standoff) and (257/686 257/685 257/723	US-PGPUB;	11:14
		257/777 257/778 257/737 257/738 257/784	EPO; JPO;	
		257/786)	DERWENT;	
			IBM_TDB	

2024099   dinegrated adj circuit) ic semiconductor   USPAT; US-RGPUB; REPO, JPO; DERWENT; IBM, TDB   USPAT; US-RGPUB; USPAT;	L	Hits	Search Text	DB	Time stamp
die chip dice   Us-PGUUB;   BPO, JPO   DERWENT;   IBM TDB   Standoff   Standoff   US-PGUUB;   EPO, JPO   DERWENT;   IBM TDB   STANDOM	Number				
2		2124099			
2			die chip dice		11:07
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Section   Sect	2	579735	flipchip (flip adj chip) bumps balls		
1575   257/686   DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO;   DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; JPO; DERWINT;   IBM TDB   USPAT;   US-FOFUB;   EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J			standoff		11:08
18M TDB   18PAT					
1575   257/686   USPĀT;   2002/06/28   11:08   EPO; JPO;   DERWENT;   IBM TDB   USPĀT;   US				1	
11:08					2222 (25 (22
REPO, JPOP, DERMENT; IRM TDB USPAT; US-PGPUB; BPO, JPOP, DERMENT   IRM TDB USPAT; US-PGPUB; BPO, JPOP, DERMENT; IRM TDB USPAT; US-PGPUB; BPO, JPOP, DERMENT; IRM TDB USPAT; US-PGPUB; BPO, JPOP, DERMENT; IRM TDB USPAT; US-PGPUB; BPOP, JPOP, DERMENT; IRM TDB USPAT; US-PGPUB; USP	3	1575	257/686		I .
DERWENT; ISM TIDE   USPAT; US-POPUB; EPO; JPO; DERWENT; ISM TIDE   USP					11:08
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4 0 257/6856 USPĀT; US-POPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US					
Second   S			257/5256		2002/06/28
EPC: JPC: DERWENT: IBM TDB USPAT: 2002/06/28 11:08 EPC: JPC: DERWENT: IBM TDB USPAT: US-PGUB; EPC: JPC: DERWENT: US-PGUB; EPC: DERWENT: US-PGUB; EPC: JPC: DERWEN	4	0	257/6856		
DERWENT; IRM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				i '	11:08
TIRM TOB USPAT;   2002/06/28   11:08					
257/685   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; DE				ì	
US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PAT;   US-PGPUB;   EPO; JPO; DERWENT;   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PAT;   US-PGPUB;   EPO; JPO; DERWENT;   IBM TDB   US-PAT;   US-PGPUB;   EPO; JPO; DERWENT;   US-PGPUB;   US-PGPU	_		257/605		2002/06/28
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18M TDB					
2481   257/723   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; US-PGPUB					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO;		0.401	057/703		2002/06/28
Table	6	2481	25 // /23		1
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7 1398 257/777 USPGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT BY DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPĀT; US				E .	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;		1200	257/777		2002/06/28
8 2304 257/778   EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	'	1398	251/111		1
8 2304 257/778   DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWE				1	11.00
8 2304 257/778				l.	
8 2304 257/778 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWE					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPĀT; US-PGPUB; EPO; JPO;		2204	257/779	_	2002/06/28
Pop	8	2304	2577776		
1931   257/737   DERWENT;   IBM TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPAT;					11.00
9 1931 257/737	1				
9 1931 257/737 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JP				-	
10	۵	1931	257/737		2002/06/28
10	"	1931	23,,,,,,,,	•	
DERWENT;   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   DERWENT;   US-PGPUB;   EPO; JPO;   DERWENT;   US-PGPUB;   US-PGPUB;   US-PGPUB;   US-PGPUB;   US-PGPUB;   US-PGPUB;   US-PGPUB;   U					
1543   257/738   IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT;		,			
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US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT;	10	1543	257/738		2002/06/28
11	10	15.5			
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
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11 1641 257/784 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT;				i	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USP	11	1641	257/784		2002/06/28
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;					
12 1783 257/786 IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US					
12 1783 257/786 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; Semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff) US-PGPUB; EPO; JPO; DERWENT;				DERWENT;	
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	12	1783	257/786	USPĀT;	2002/06/28
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; EPO; JPO; DERWENT;					11:08
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  USPĀT; US-PGPUB; EPO; JPO; DERWENT;				1	
semiconductor die chip dice) (flipchip US-PGPUB; 11:09 (flip adj chip) bumps balls standoff) EPO; JPO; DERWENT;	13	2602195	((integrated adj circuit) ic		2002/06/28
(flip adj chip) bumps balls standoff) EPO; JPO; DERWENT;			semiconductor die chip dice) (flipchip	•	11:09
DERWENT;	1		(flip adj chip) bumps balls standoff)	EPO; JPO;	
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1		257/737 257/738 257/784 257/786	US-PGPUB;	11:09
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
15	124853	438/\$7.ccls.	USPAT;	2002/06/28
			US-PGPUB;	11:09
			EPO; JPO;	
			DERWENT;	
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16	91119	361/\$7.ccls.	USPAT;	2002/06/28
			US-PGPUB;	11:09
			EPO; JPO;	
			DERWENT;	
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17	4715		USPAT;	2002/06/28
		standoff) and (257/686 257/685 257/723	US-PGPUB;	11:14
		257/777 257/778 257/737 257/738 257/784	EPO; JPO;	
		257/786)	DERWENT;	
			IBM_TDB	